

IN THE SPECIFICATION:

Please amend the paragraph beginning at page 5, line 11, as follows:

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The semiconductor device of the illustrative embodiment is featured in that a first back-illuminated semiconductor image sensing or pickup element 10 is disposed so that it is stacked or laminated over a second semiconductor image pickup element 20 made of a chosen semiconductor material different from that of the first semiconductor image pickup element 10 in such a manner that respective photosensitive regions (light absorption layers) 15, 22 of the first and second first semiconductor image pickup elements 10, 20 are placed in close proximity to each other. Since the back-illuminated semiconductor image pickup element is such that its photosensitive region is placed on the opposite side to the light incident plane thereof, laminating the first and second semiconductor image pickup elements over each other makes it possible to permit the photosensitive regions of respective semiconductor image pickup elements to come closer to each other, thus causing the focusing position of an image of a target body being detected to become adjacent, which may in turn enable effectuation of successful image pickup operations while at the same time suppressing or minimizing any possible image defocusing or blooming defects. Optionally the image pickup elements 10, 20 may be formed of one-dimensional or two-dimensional image sensors. A detailed explanation will be given below.

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